

## N-Channel 200 V (D-S) MOSFET

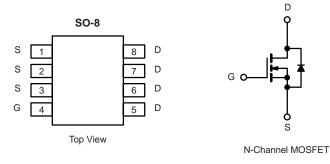
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)		
200	0.260 at V <sub>GS</sub> = 10 V	3		

#### **FEATURES**

- TrenchFET<sup>®</sup> Power MOSFET
- 175 °C Junction Temperature
- PWM Optimized
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC

#### **APPLICATIONS**

• Primary Side Switch



<b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_A = 25 \text{ °C}$ , unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage		V <sub>DS</sub>	200	V		
Gate-Source Voltage			± 20	v		
	T <sub>C</sub> = 25 °C	1_	3			
Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 125 °C	I <sub>D</sub>	2.7			
Pulsed Drain Current	I <sub>DM</sub>	10	А			
Continuous Source Current (Diode Conduction)	۱ <sub>S</sub>	6				
Avalanche Current	I <sub>AS</sub>	6	1			
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	18	mJ		
Movimum Dower Dissinction	T <sub>C</sub> = 25 °C	P	96 <sup>b</sup>	10/		
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3 <sup>a</sup>	W		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stq</sub>	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
	t ≤ 10 s	- R <sub>thJA</sub>	15	18	°C/W	
Junction-to-Ambient <sup>a</sup>	Steady State		40	50		
Junction-to-Case (Drain)	•	R <sub>thJC</sub>	0.85	1.1		

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. See SOA curve for voltage derating.





Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$	200				
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2		4	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1	μA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 \text{ °C}$	<sub>J</sub> = 125 °C 50		50		
		$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 \text{ °C}$			250	1	
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 V, V_{GS} = 10 V$	40			А	
		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 3 \text{ A}$		0.260			
	P	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A, T <sub>J</sub> = 125 °C		0.310			
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A, T <sub>J</sub> = 175 °C		0.330		Ω	
		V <sub>GS</sub> = 6 V, I <sub>D</sub> = 3 A		0.292			
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 3 A		35		S	
Dynamic <sup>a</sup>							
Input Capacitance	C <sub>iss</sub>			1800		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS}$ = 0 V, $V_{DS}$ = 25 V, F = 1 MHz		180			
Reverse Transfer Capacitance	C <sub>rss</sub>			80			
Total Gate Charge <sup>c</sup>	Qg			34	51		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS}$ = 100 V, $V_{GS}$ = 10 V, $I_D$ = 3 A		8		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			12			
Gate Resistance	Rg		0.5		2.9	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			15	25		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 100 V, R <sub>L</sub> = 5.2 $\Omega$		50	75	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 3 \text{ A}, \text{ V}_{\text{GEN}} = 10 \text{ V}, \text{ R}_g = 2.5 \Omega$		30	45		
Fall Time <sup>c</sup>	t <sub>f</sub>			60	90		
Source-Drain Diode Ratings and Char	acteristics (1	Γ <sub>C</sub> = 25 °C)					
Pulsed Current	I <sub>SM</sub>				5	А	
Diode Forward Voltage <sup>b</sup>	$V_{SD}$	I <sub>F</sub> = 3 A, V <sub>GS</sub> = 0 V		0.9	1.5	V	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 3 A, dl/dt = 100 A/µs		180	250	ns	

Notes:

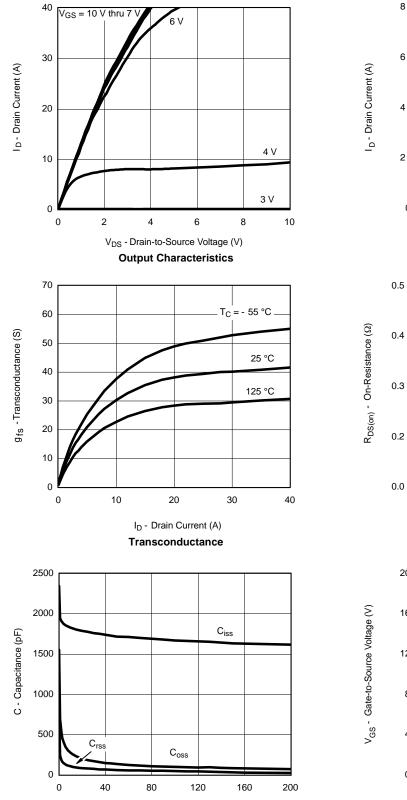
a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

c. Independent of operating temperature.

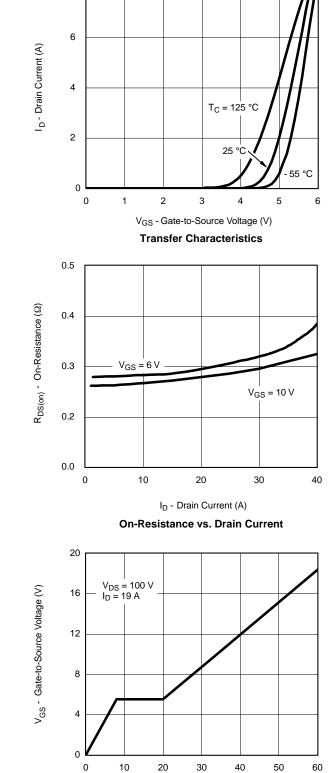
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





V<sub>DS</sub> - Drain-to-Source Voltage (V) Capacitance

#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Q<sub>g</sub> - Total Gate Charge (nC)

Gate Charge

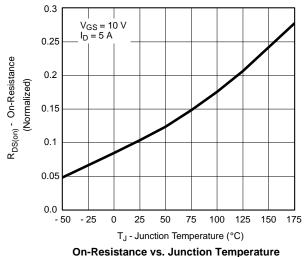


T<sub>J</sub> = 25 °C

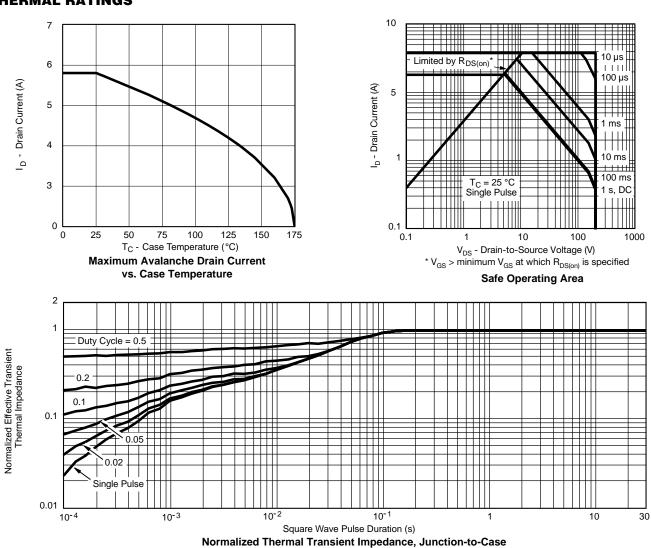
0.9

1.2

#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)







100

10

1

0

0.3

T<sub>J</sub> = 150 °C

0.6

Source-Drain Diode Forward Voltage

V<sub>SD</sub> - Source-to-Drain Voltage (V)

I<sub>S</sub> - Source Current (A)



### SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012

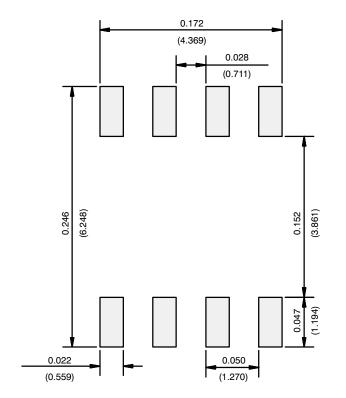




	MILLIMETERS		INC	HES	
DIM	Min	Мах	Min	Max	
A	1.35	1.75	0.053	0.069	
A <sub>1</sub>	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					



**RECOMMENDED MINIMUM PADS FOR SO-8** 



Recommended Minimum Pads Dimensions in Inches/(mm)



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